

DESCRIPTION

The M5M54R08J is a family of 524288-word by 8-bit static RAMs, fabricated with the high performance CMOS silicon gate process and designed for high speed application.

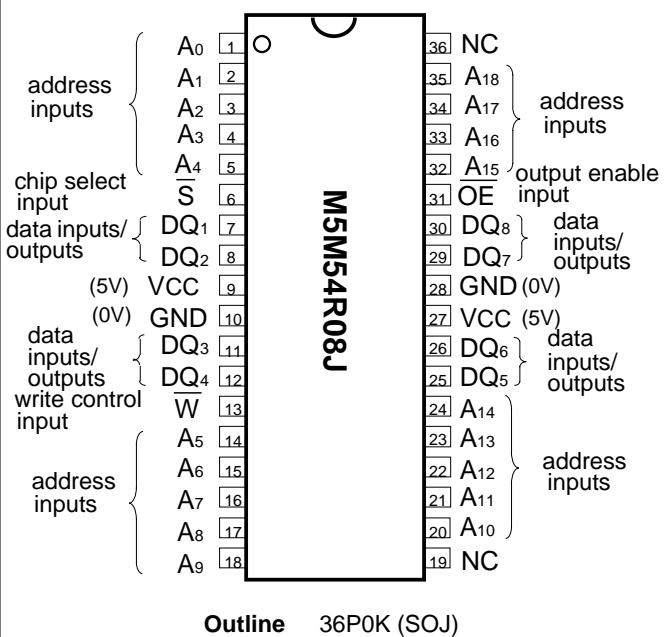
The M5M54R08J is offered in a 36-pin plastic small outline J-lead package(SOJ).

These device operate on a single 5V supply, and are directly TTL compatible. They include a power down feature as well.

FEATURES

- Fast access time M5M54R08J-12 12ns(max)
 M5M54R08J-15 15ns(max)
- Low power dissipation Active 550mW(typ)
 Stand by 5mW(typ)
- Single +5V power supply
- Fully static operation : No clocks, No refresh
- Common data I/O
- Easy memory expansion by S
- Three-state outputs : OR-tie capability
- OE prevents data contention in the I/O bus
- Directly TTL compatible : All inputs and outputs

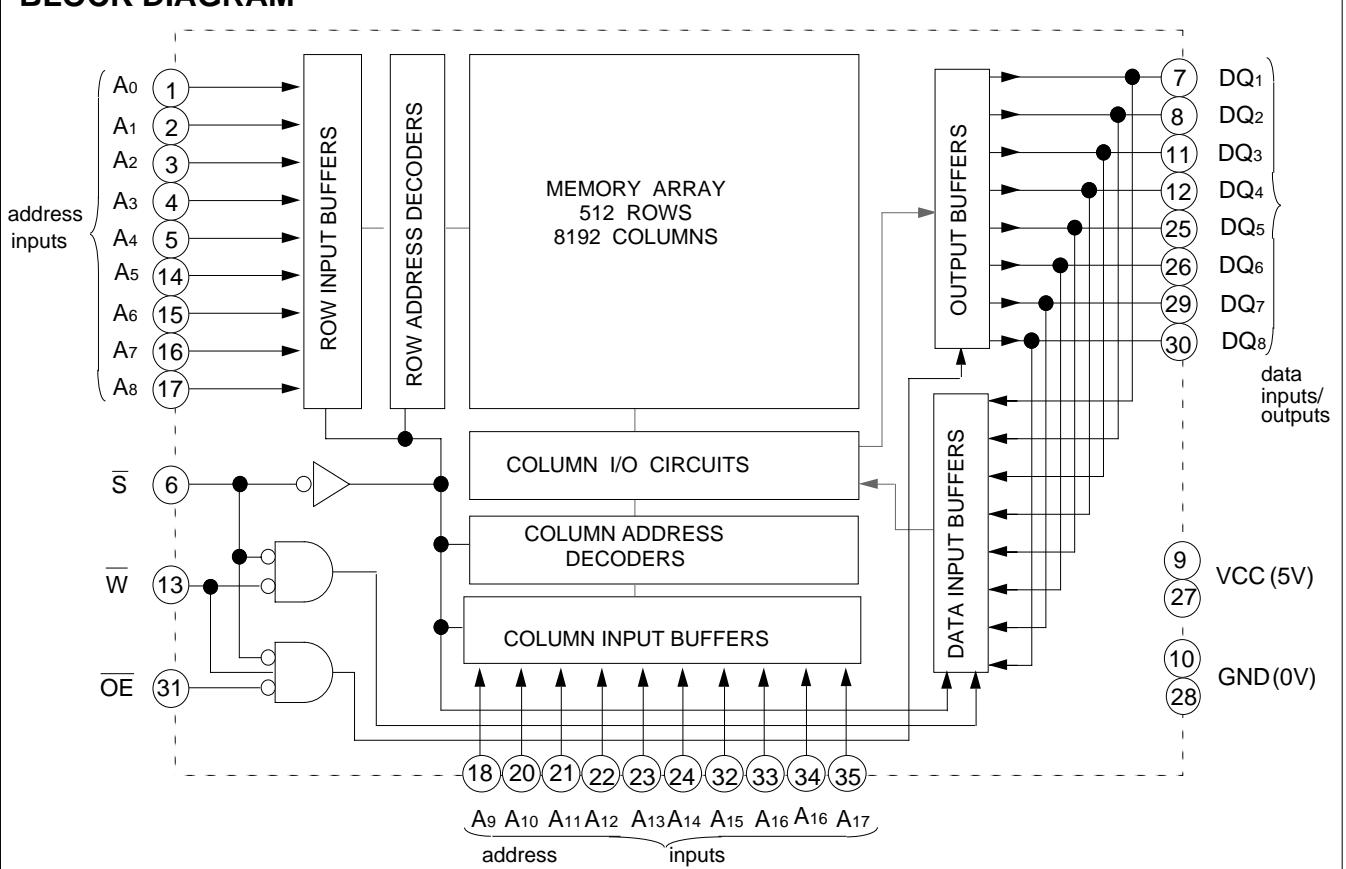
PIN CONFIGURATION (TOP VIEW)



APPLICATION

High-speed memory units

BLOCK DIAGRAM



PACKAGE

36pin 400mil SOJ

FUNCTION

The operation mode of the M5M54R08J is determined by a combination of the device control inputs \bar{S} , \bar{W} and \bar{OE} . Each mode is summarized in the function table.

A write cycle is executed whenever the low level \bar{W} overlaps with the low level \bar{S} . The address must be set-up before the write cycle and must be stable during the entire cycle.

The data is latched into a cell on the trailing edge of \bar{W} or \bar{S} , whichever occurs first, requiring the set-up and hold time relative to these edge to be maintained. The output enable input \bar{OE} directly controls the output stage. Setting the \bar{OE} at a high level, the output stage is in a high impedance state, and the data bus

contention problem in the write cycle is eliminated.

A read cycle is executed by setting \bar{W} at a high level and \bar{OE} at a low level while \bar{S} are in an active state ($\bar{S}=L$).

When setting \bar{S} at high level, the chip is in a non-selectable mode in which both reading and writing are disable. In this mode, the output stage is in a high-impedance state, allowing OR-tie with other chips and memory expansion by \bar{S} .

Signal \bar{S} controls the power-down feature. When \bar{S} goes high, power dissipation is reduced extremely. The access time from \bar{S} is equivalent to the address access time.

FUNCTION TABLE

\bar{S}	\bar{W}	\bar{OE}	Mode	DQ	Icc
H	X	X	Non selection	High-impedance	Stand by
L	L	X	Write	Din	Active
L	H	L	Read	Dout	Active
L	H	H		High-impedance	Active

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings		Unit
			Min	Typ	
Vcc	Supply voltage	With respect to GND	-3.5 * ~ 7		V
VI	Input voltage		-3.5 * ~ VCC+0.3		V
VO	Output voltage		-3.5 * ~ VCC+0.3		V
Pd	Power dissipation	Ta=25°C	1000		mW
Topr	Operating temperature		0 ~ 70		°C
Tstg(bias)	Storage temperature (bias)		-10 ~ 85		°C
Tstg	Storage temperature		-65 ~ 150		°C

*Pulse width ≤ 20ns, In case of DC:-0.5V

DC ELECTRICAL CHARACTERISTICS (Ta=0 ~ 70 °C, Vcc=5V±10% unless otherwise noted)

Symbol	Parameter	Condition	Limits			Unit	
			Min	Typ	Max		
VIH	High-level input voltage		2.2		Vcc+0.3	V	
VIL	Low-level input voltage		-0.3		0.8	V	
VOH	High-level output voltage	IOH = -4mA	2.4			V	
VOL	Low-level output voltage	IOL= 8mA			0.4	V	
II	Input current	VI = 0~Vcc			2	μA	
IOZ	Output current in off-state	VI(\bar{S})= VIH VO= 0~Vcc			10	μA	
Icc1	Active supply current (TTL level)	VI(\bar{S})= VIL other inputs VIH or VIL Output-open(duty 100%)	AC	12ns cycle		170	mA
				15ns cycle		160	
			DC		110	120	
Icc2	Stand by current (TTL level)	VI(\bar{S})= VIH	AC	12ns cycle		85	mA
				15ns cycle		80	
			DC			60	
Icc3	Stand by current	VI(\bar{S})= Vcc≥0.2V other inputs VI≤0.2V or VI≥Vcc-0.2V			1	10	mA

CAPACITANCE ($T_a=0 \sim 70^\circ C$, $V_{cc}=5V \pm 10\%$ unless otherwise noted)

Symbol	Parameter	Test Condition	Limit			Unit
			Min	Typ	Max	
C_I	Input capacitance	$V_I = GND, V_I = 25mVrms, f = 1MHz$			7	pF
C_O	Output capacitance	$V_O = GND, V_O = 25mVrms, f = 1MHz$			8	pF

Note 1: Direction for current flowing into an IC is positive (no mark).

2: Typical value is $V_{cc}=5V, T_a=25^\circ C$

3: C_I, C_O are periodically sampled and are not 100% tested.

AC ELECTRICAL CHARACTERISTICS ($T_a=0 \sim 70^\circ C$, $V_{cc}=5V \pm 10\%$ unless otherwise noted)

(1) MEASUREMENT CONDITION

Input pulse levels $V_{IH}=3.0V, V_{IL}=0.0V$

Input rise and fall time $3ns$

Input timing reference levels $V_{IH}=1.5V, V_{IL}=1.5V$

Output timing reference levels $V_{OH}=1.5V, V_{OL}=1.5V$

Output loads Fig1 ,Fig2

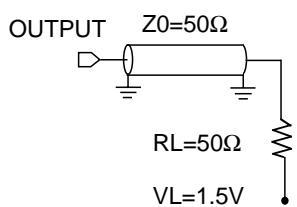


Fig.1 Output load

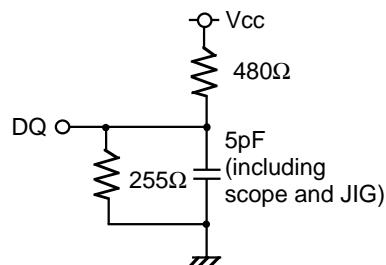


Fig.2 Output load for t_{en}, t_{dis}

(2)READ CYCLE

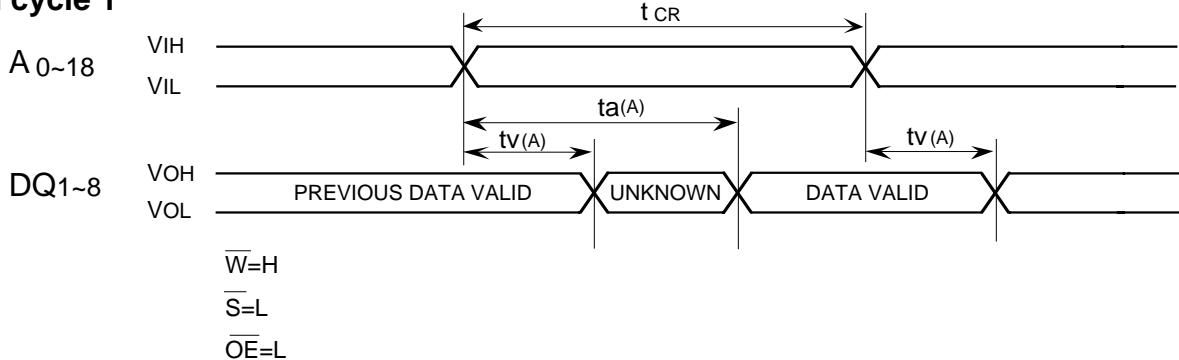
Symbol	Parameter	Limits				Unit	
		M5M54R08J -12		M5M54R08J -15			
		Min	Max	Min	Max		
t _{CR}	Read cycle time	12		15		ns	
t _{a(A)}	Address access time		12		15	ns	
t _{a(S)}	Chip select access time		12		15	ns	
t _{a(OE)}	Output enable access time		6		8	ns	
t _{dis(S)}	Output disable time after S high	0	6	0	7	ns	
t _{dis(OE)}	Output disable time after OE high	0	6	0	7	ns	
t _{en(S)}	Output enable time after S low	0		0		ns	
t _{en(OE)}	Output enable time after OE low	0		0		ns	
t _{v(A)}	Data valid time after address change	3		3		ns	
t _{PU}	Power-up time after chip selection	0		0		ns	
t _{PD}	Power-down time after chip selection		12		15	ns	

(3)WRITE CYCLE

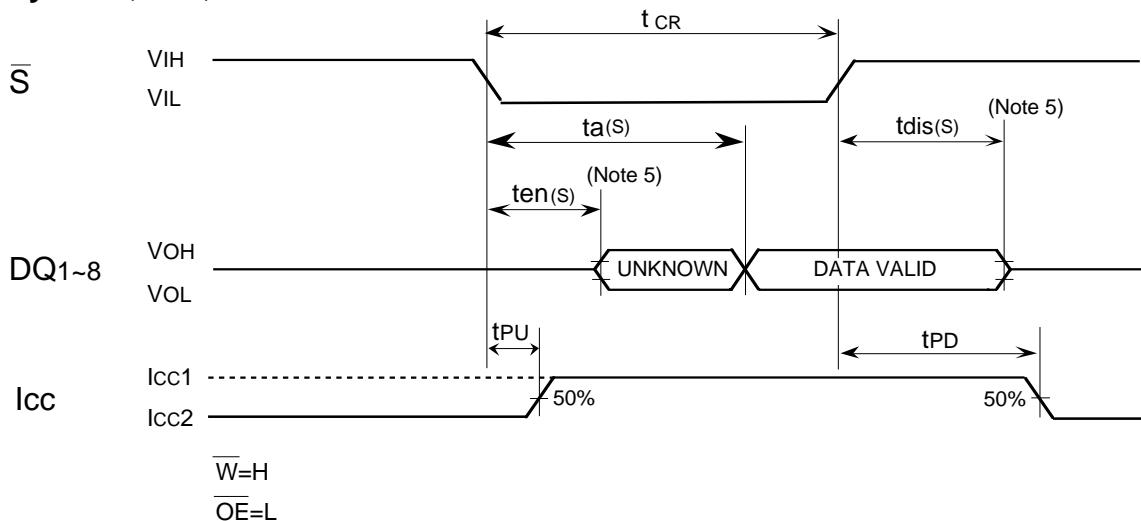
Symbol	Parameter	Limits				Unit	
		M5M54R08J -12		M5M54R08J -15			
		Min	Max	Min	Max		
t _{CW}	Write cycle time	12		15		ns	
t _{w(W)}	Write pulse width	10		12		ns	
t _{su(A)1}	Address setup time(\bar{W})	0		0		ns	
t _{su(A)2}	Address setup time(\bar{S})	0		0		ns	
t _{su(S)}	Chip select setup time	10		12		ns	
t _{su(D)}	Data setup time	6		7		ns	
t _{h(D)}	Data hold time	0		0		ns	
t _{rec(W)}	Write recovery time	1		1		ns	
t _{dis(W)}	Output disable time after \bar{W} low	0	6	0	7	ns	
t _{dis(OE)}	Output disable time after OE high	0	6	0	7	ns	
t _{en(W)}	Output enable time after \bar{W} high	0		0		ns	
t _{en(OE)}	Output enable time after OE low	0		0		ns	
t _{su(A-WH)}	Address to \bar{W} High	10		12		ns	

(4)TIMING DIAGRAMS

Read cycle 1



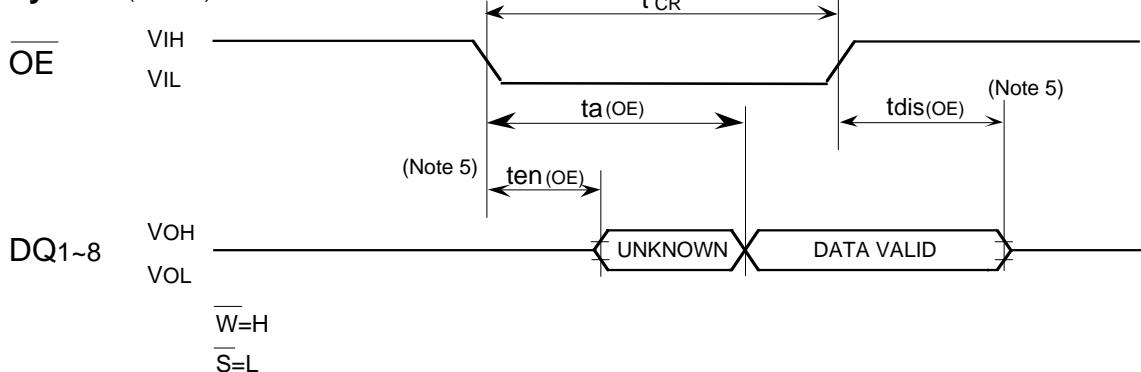
Read cycle 2 (Note 4)



Note 4. Addresses valid prior to or coincident with \overline{S} transition low.

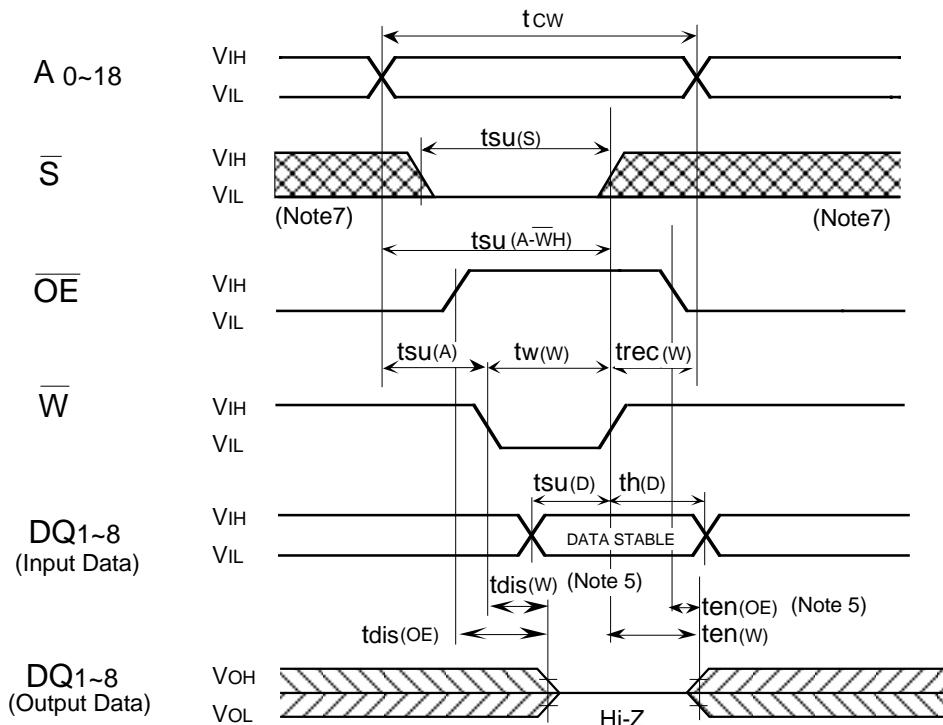
5. Transition is measured $\pm 500\text{mV}$ from steady state voltage with specified loading in Figure 2.

Read cycle 3 (Note 6)

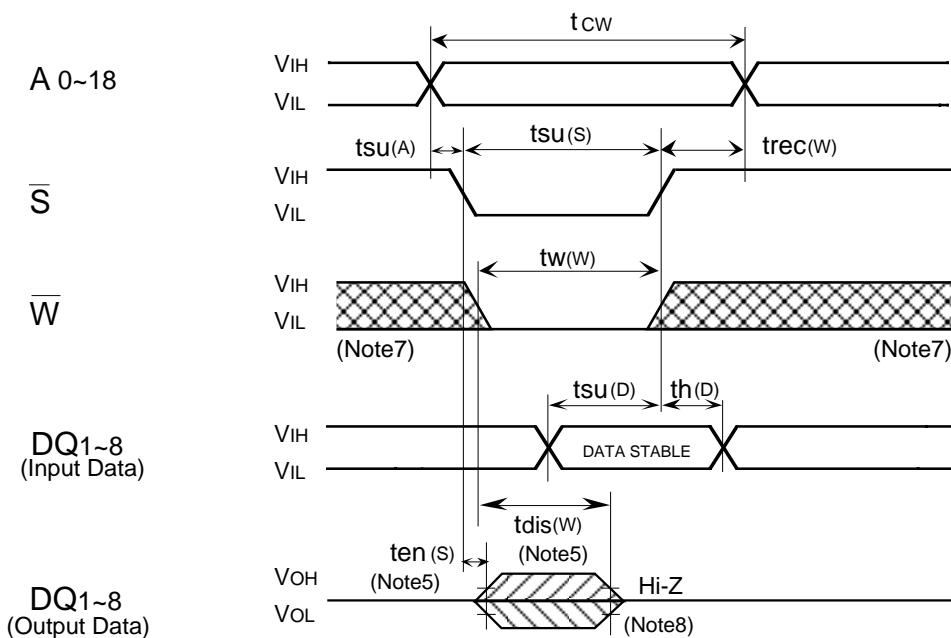


Note 6. Addresses and \overline{S} valid prior to \overline{OE} transition low by $(t_{a(A)} - t_{a(OE)})$, $(t_{a(S)} - t_{a(OE)})$

Write cycle (W control mode)



Write cycle (S control mode)



Note 7: Hatching indicates the state is don't care.

8: When the falling edge of W is simultaneous or prior to the falling edge of S, the output is maintained in the high impedance.

9: ten,tdis are periodically sampled and are not 100% tested.